

Title of the invention: Process for the manufacture of a donor substrate for the transfer of a piezoelectric layer and process for transfer of a piezoelectric layer onto a support substrate

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Abstract

The invention relates to a process for the manufacture of a donor substrate for the transfer of a piezoelectric layer onto a support substrate, comprising the stages of providing a handling substrate, in particular a silicon-based substrate, providing a piezoelectric substrate, depositing a polymer layer on the handling substrate or the piezoelectric substrate, forming an intermediate layer on a free surface of the piezoelectric substrate, assembling the piezoelectric substrate on the handling substrate in such a way that the intermediate layer formed on the piezoelectric substrate is sandwiched between the polymer layer and the piezoelectric substrate in order to form the donor substrate. The invention also relates to a donor substrate manufactured by such a process and to a process for the transfer of a piezoelectric layer using such a donor substrate.

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[Figure 1a]